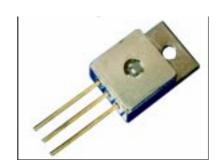
Laser Diode in TO-220 Package 1.0 W cw (Class 4 Laser Product)

SPL 2Yxx (SFH 4874x1)

Features

- Efficient radiation source for pulsed and cw-operation
- Reliable InGa(AI)As strained layer quantum-well material
- Small TO-220 package with efficient thermal coupling
- Includes thermistor to control temperature/wavelength
- Single emitting area 200 μm × 1 μm
- Cylindrical correction for a near circular farfield pattern



Applications

- Pumping solid state lasers (Nd: YAG, Yb: YAG, ...)
- Medical applications
- Laser soldering
- Energy transmission
- Testing and measuring applications

Туре	Old Type (as of Oct. 1996)	Wavelength *)	Ordering Code
SPL 2Y81 SPL 2Y85 SPL 2Y94 SPL 2Y98	SFH 487401 SFH 487421 SFH 487441	808 nm 850 nm 940 nm 980 nm	Q62702-P367 Q62702-P1677 Q62702-P1630 on request

^{*)} Other wavelengths in the range of 780 nm ... 980 nm are available on request.

Maximum Ratings

 $(T_{A} = 25 \, {}^{\circ}\text{C})$

Parameter	Symbol	Values		;	Unit
		min.	typ.	max.	
Output power (continuous wave) 1)	P_{opt}	_	_	1.1	W
Output power (quasi-continuous wave) 1) $(t_p \le 150 \mu s, duty cycle \le 1\%)$	$P_{\sf qcw}$	_	_	1.5	W
Reverse voltage	V_{R}	_	_	3	V
Operating temperature	$T_{\sf op}$	- 10		+ 60	°C
Storage temperature	$T_{ m stg}$	- 40		+ 85	°C
Maximum soldering temperature, max. 5 s	$T_{\rm s}$	_	_	250	°C

¹⁾ Optical power measurements refer to a detector with NA = 0.6

Diode Characteristics

 $(T_A = 25 \, ^{\circ}\text{C})$

Parameter		Symbol	Values			Unit
			min.	typ.	max.	
Emission wavelength 1)		λ_{peak}	803 840 935	808 850 940	813 860 945	nm
Spectral width (FWHM) 1)		Δλ	2		nm	
Output power 2)		P_{opt}	1.0		W	
Differential efficiency 2)	808 nm 850 nm 940 nm	η	0.75 0.75 0.70	0.95 0.85 0.80	1.1 1.0 0.9	W/A
Threshold current	808 nm 850 nm 940 nm	I_{th}	0.40 0.30 0.30	0.45 0.40 0.35	0.55 0.50 0.40	А
Operating current 1)	808 nm 850 nm 940 nm	$I_{\sf op}$	1.3 1.3 1.4	1.5 1.5 1.6	1.8 1.8 1.8	А
Operating voltage 1)		V_{op}		2.0	•	V
Differential series resistance		$r_{\rm s}$	_	0.2	0.4	Ω
Characteristic temperature (threshold) 3)		T_0	150		K	
Temperature coefficient of operating current		$\partial I_{\text{op}} / \partial T$	0.5		%/K	
Temperature coefficient of wavelength 4)		$\partial \lambda / \partial T$	0.25	0.27	0.30	nm/K
Thermal resistance (junction → heat sink)		$R_{th\;JA}$		10		K/W

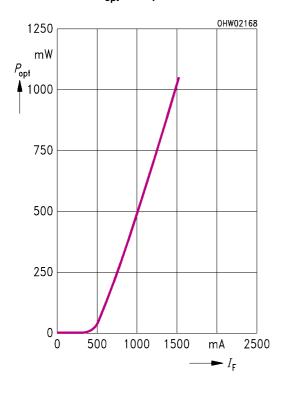
- 1) Standard operating conditions refer to 1 W cw measured with NA = 0.6
- 2) Optical power measurements refer to a detector with NA = 0.6
- 3) Model for the thermal behavior of threshold current: $I_{th}(T_2) = I_{th}(T_1) \times \exp(T_2 T_1)/T_0$
- 4) Depending on emission wavelength

NTC Thermistor

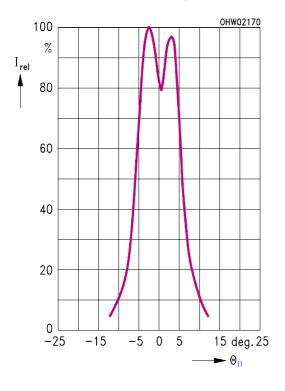
Parameter	Symbol	Typ. Values	Unit
Resistance at room temperature (25 °C)	R_{NTC}	10	kΩ

Optical Characteristics ($T_A = 25$ °C)

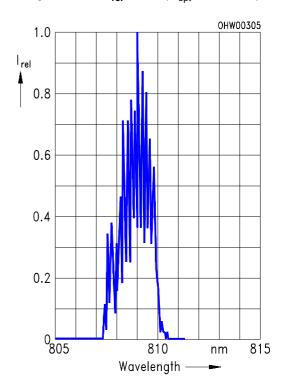
Radiant Power P_{opt} vs I_{F}



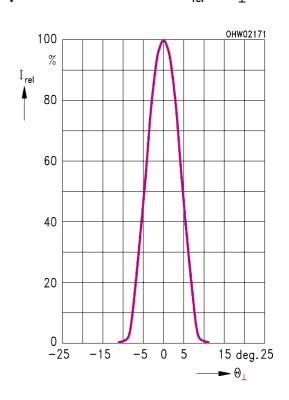
Farfield Distribution Parallel to Junction $I_{\rm rel}$ vs θ_{\parallel}



Mode Spectrum I_{rel} vs λ (P_{opt} = 1.0 W)



Farfield Distribution Perpendicular to Junction $I_{\rm rel}$ vs θ_{\perp}



Notes for Operation

1. Eye Protection

This laser is a **Class 4 Laser** product.

Refer to the relevant safety regulations for protection during handling and operation.

2. Overload Protection

The specified values are valid as long as the diode has not been not overloaded. Voltage spikes from the power supply unit, even when applied for nanoseconds only, may cause irreversible damage to the laser diode. Such spikes may occur when the power supply is turned on or off, or they may reach the laser diode from the line via the coupling capacitance of electronically controlled devices.

The power supply should therefore be provided with appropriate protection circuits.

Handling Notes

1. Package

To avoid electrostatic damage it is recommended to observe the same rules as for handling MOS-devices.

2. Mechanical Attachment

- 2.1 Mounting hole (suitable for M 2.5) Because of the good thermal conductivity of the TO 220 base plate (copper) the heat loss is properly dissipated even if the component is attached on one side only. Some mounting techniques are shown below (Fig. 1 − 3).
- 2.2 For exact positioning of the TO component and other parts, e.g. lenses, the TO 220 package can be attached with appropriate clamping devices or screws (max. M 2.5).

3. Soldering

When soldering the TO base to a heat sink, do not exceed the following limits:

max. soldering temperature: 125 °C
max. soldering time: 1 min.

Mounting Techniques

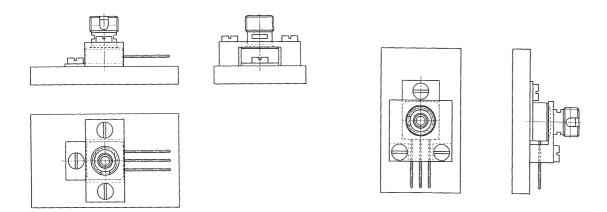


Figure 1 Figure 2

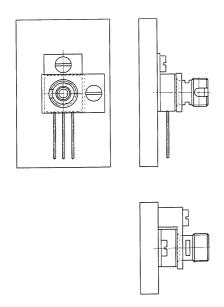


Figure 3

Package Outlines

(Dimensions in mm, unless specified).

